

Abstract

The present invention is a solder coated material having a large amount of solder adhered to a difficult to solder material such as Kovar or Alloy 42 and a method which can adhere a sufficient amount of solder to a difficult to solder material without using flux. An electroplated coating is applied to a portion to be soldered of a difficult to solder material, the difficult to solder material is then passed through molten solder to which ultrasonic waves are applied, and a large amount of solder is adhered only to solder plated portions.

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